|  |  |  |  |  |  |  |  |  |  |  |
| --- | --- | --- | --- | --- | --- | --- | --- | --- | --- | --- |
| Company: UC Berkeley | | | | | | | Date: 10/20/17 | | | |
| Contact Name: Taehwan Kim | | | | | | | Project Name: DODOS TIA | | | |
| Address: 2108 Allston Way, Suite 200 | | | | | | | Description: | | | |
| Phone: 5102953549 | | Email: taehwan@berkeley.edu | | | | | \*Standard Turn: 10 Business Days | | | |
| \*Expedited Turn Options available for an Additional Charge | | | | | | | 1-Day | 3-Day | | 5-Day |
|  | | | | | | | 1st Article Required (additional charge) | | | |
| **PACKAGE:** Ceramic Plastic LCC QFN PGA DIP | | | | | | | COB: Other: | | | |
| Package Supplied by: Customer  Advotech | | | | | | | Quantity of die to be Packaged: 10 | | | |
| Lid Supplied by: Customer  Advotech | | | | | | | Desired Package Lead Count: 39 | | | |
| **DIE SIZE:** | Length: 2000u | | Width: 1000u | Height: | | Bond Pad  Opening Width: 52u | | | Pad Pitch - Center to Center: 188u | |
| Die surface contact OK? Yes No | | | | | Details: | | | | | |

Die Attach Material: Non-conductive Epoxy  Conductive epoxy  Solder:  Advotech Discretion

|  |  |  |  |  |  |
| --- | --- | --- | --- | --- | --- |
| Flip Chip | Bump Alloy: | Bump Ht: | Bump Pitch: | Bump Dia: | Underfill: |
| **WIRE BONDING** Diagram - (*Please send now if available. Diagram can be supplied later if this is a budgetary quote.*)  Provided  Will Provide Later **Wire Count**: 39 | | | | | |

Bond Wire Type: Au AlSi Cu Ag  Advotech Discretion

Bond Wire Size: 0.7 0.8 0.9 1.0 1.2 1.3 1.5 2.0mil  Advotech Discretion

Bond Type: Ball Bond Wedge Bond Ribbon Bond Stud Bump  Advotech Discretion

Package Sealing Preference: Taped Lid (Removable) Tacked Lid Sealed Lid No Lid Other:

**PCB Assembly, SMT & Chip on Board (COB):** PCB Size: (L x W x Thick):

|  |  |  |  |  |  |  |  |  |  |  |  |  |  |
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| QTY: | Material: | | | Double Sided Assy | | | | | Pb-free Solder | | | SMT assembly by Advotech | |
| SMDs provided by:  Customer Advotech | | | | | | Parts on Reels? : | | | | # of Through-hole Parts per PCB: | | | |
|  | | | | | | |  | | | # of SMDs per Assembly: | | | |
| Die (Chip) Protection: | | UV Glob Top Clear | | | | | | Glob Top Black | | | Other: | | |
| Glob Top (if applicable): | | Wires Only | | | | | | Wires & Chip | | | | |  |
| Will the assembly be exposed to heat/cold: | | | | | Yes  No If yes, what temp: | | | | | | | | |
| PCB cleaning required | | | Any Special Instructions? | | | | | | | | | | |

**Reliability Testing:** Wire Pull Destructive Non-destructive with specified limits:

No Testing Die Shear Destructive Non-destructive with specified limits:   
 X-Ray Temp-Cycle Other:

**Functional Testing:**  None  Test description:

|  |  |
| --- | --- |
| Additional Info: | |
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| Advotech Engineering Notes: | |
|  | |
|  | |
| Reviewed By: | Date Reviewed: |